

IN THE SPECIFICATION:

Please replace paragraph [0001] with the following.

[0001] This application is a divisional of application Serial No. 10/150,901, filed May 17, 2002, pending, which is related to U.S. Patent Application Serial No. 09/944,465 filed August 30, 2001, now U.S. Patent No. 6,756,251, issued June 29, 2004, and entitled MICROELECTRONIC DEVICES AND METHODS OF MANUFACTURE, METHOD OF MANUFACTURING MICROELECTRONIC DEVICES, INCLUDING METHODS OF UNDERFILLING MICROELECTRONIC COMPONENTS THROUGH AN UNDERFILL APERTURE, and to the following U.S. Patent Applications also filed May 17, 2002: Serial No. 10/150,893, now U.S. Patent No. 7,145,225, issued December 5, 2006, entitled INTERPOSER CONFIGURED TO REDUCE THE PROFILES OF SEMICONDUCTOR DEVICE ASSEMBLIES AND PACKAGES INCLUDING THE SAME AND METHODS; Serial No. 10/150,892, entitled METHOD AND APPARATUS FOR FLIP-CHIP PACKAGING PROVIDING TESTING CAPABILITY; Serial No. 10/150,516, now U.S. Patent No. 7,112,520, issued September 26, 2006, entitled SEMICONDUCTOR DIE PACKAGES WITH RECESSED INTERCONNECTING STRUCTURES AND METHODS FOR ASSEMBLING THE SAME; Serial No. 10/150,653, now U.S. Patent No. 7,161,237, issued January 9, 2007, entitled FLIP CHIP PACKAGING USING RECESSED INTERPOSER TERMINALS; and Serial No. 10/150,902, now U.S. Patent No. 6,975,035, issued December 13, 2005, entitled METHOD AND APPARATUS FOR DIELECTRIC FILLING OF FLIP CHIP ON INTERPOSER ASSEMBLY.